

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Withdrawn) Atomic layer deposition arrangement comprising:  
    an evacuable chamber,  
    at least two atomic layer deposition sources within the chamber, wherein each atomic layer deposition source is isolated from the remainder of the chamber, and  
    means for conveying substrate through the evacuable chamber.
2. (Withdrawn) Atomic layer deposition arrangement according to claim 1 wherein the means for conveying substrate comprises a rotatable drum.
3. (Withdrawn) Atomic layer deposition arrangement according to claim 1 further comprising a grounded shield for each atomic layer deposition source.
4. (Withdrawn) Atomic layer deposition arrangement according to claim 1 further comprising a substrate source chamber adjacent to the evacuable chamber.
5. (Withdrawn) Atomic layer deposition arrangement according to claim 4 wherein the substrate source chamber comprises a first rotatable drum and a second rotatable drum, the first rotatable drum having polymer film wrapped around the drum, wherein the polymer film is conveyed into the evacuable chamber, and the second rotatable drum receives the polymer film after the polymer film exits the evacuable chamber.

6. (Withdrawn) Atomic layer deposition arrangement according to claim 5 wherein the polymer film comprises at least one selected from the group consisting of polyethylene terephthalate, polyacrylate, polypropylene, low density polyethylene, high density polyethylene, ethylene vinyl alcohol, polyphenylpropyleneoxide, polyvinylidene chloride and polyamides.

7. (Withdrawn) Atomic layer deposition arrangement according to claim 6 wherein the polymer film comprises polyethylene terephthalate.

8. (Currently Amended) A method for preparing a coated substrate comprising:  
providing an atomic layer deposition arrangement comprising an evacuable chamber, and at least two atomic layer deposition sources within the chamber, wherein each atomic layer deposition source is isolated from the remainder of the chamber,  
conveying a polymer film substrate past each atomic layer deposition source in succession, and  
exposing the substrate to each atomic layer deposition source as the substrate is conveyed past.

9. (Currently amended) A method according to claim 8 wherein conveying as a substrate past each atomic layer deposition source comprises carrying the substrate on a rotatable drum located in the chamber.

10-11. (Canceled)

12. (Currently amended) A method according to claim ~~44~~ 8 wherein the polymer is polyethylene terephthalate, low density polyethylene, high density

polyethylene, polypropylene, polycarbonate, polyvinylidene chloride, ethylene vinyl alcohol, polyacrylate, polyamide or combinations thereof.

13. (Previously presented) A method according to claim 8 wherein at least one atomic layer deposition source is a source of trimethylaluminum.

14. (Previously presented) A method according to claim 15 wherein the oxidizing agent is oxygen, nitrous oxide, or ozone.

15. (Previously presented) A method according to claim 8 wherein at least one atomic layer deposition source is a source of oxidizing agent.

16. (Canceled)

17. (Previously presented) A method according to claim 8 wherein conveying a substrate past each atomic layer deposition source comprises  
    providing a rotatable substrate source drum having substrate film wrapped there around, and providing a rotatable collection drum,  
    rotating the substrate source drum and conveying the substrate film into the chamber, and  
    rotating the collection drum and receiving the substrate film exiting the chamber.

18. (Previously presented) A method according to claim 8 further comprising introducing an inert gas into the chamber.

19. (Currently amended) A method according to claim 8 18 wherein the inert gas is argon or oxygen.

20. (Currently amended) A method according to claim 8 wherein ~~the substrate is a polymer film and wherein~~ a barrier coating having a thickness of 400 Å to 50 Å is formed on the substrate ~~polymer film~~.